Spartan-IIE 1.8V FPGA Family: DC and Switching Characteristics

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Product Specification

Definition of Terms

In this document, some specifications may be designated as Advance or Preliminary. These designations are based on the more detailed timing information used by the development system and reported in the output files. These terms are defined as follows:

Advance: Initial estimates based on simulation and/or extrapolation from other speed grades, devices, or families. Values are subject to change. Use as estimates, not for production.

Preliminary: Based on characterization. Further changes are not expected.

Except for pin-to-pin input and output parameters, the AC parameter delay specifications included in this document are derived from measuring internal test patterns. All specifications are representative of worst-case supply voltage and junction temperature conditions. The parameters included are common to popular designs and typical applications. All specifications are subject to change without notice.

DC Specifications

Absolute Maximum Ratings(1)

Symbol	Description	Min	Max	Units
V_{CCINT}	Supply voltage relative to GND	–0.5	2.0	V
V_{CCO}	Supply voltage relative to GND	–0.5	4.0	V
V_{REF}	Input reference voltage	–0.5	4.0	V
V_{IN}	Input voltage relative to GND(2,3)	–0.5	4.0	V
V_{TS}	Voltage applied to 3-state output(3)	–0.5	4.0	V
T_{STG}	Storage temperature (ambient)	–65	+150	°C
T_J	Junction temperature	-	+125	°C

Notes:
1. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time may affect device reliability.
2. V_{IN} should not exceed V_{CCO} by more than 3.6V over extended periods of time (e.g., longer than a day).
3. Maximum DC overshoot must be limited to either V_{CCO} + 0.5V or 10 mA, and undershoot must be limited to –0.5V or 10 mA, whichever is easier to achieve. The Maximum AC conditions are as follows: The device pins may undershoot to –2.0V or overshoot to V_{CCO} + 2.0V, provided this over/undershoot lasts no more than 11 ns with a forcing current no greater than 100 mA.
4. For soldering guidelines, see the Packaging Information on the Xilinx website.

Recommended Operating Conditions

Symbol	Description		Min	Max	Units
T_J	Junction temperature	Commercial	0	85	°C
		Industrial	–40	100	°C
V_{CCINT}	Supply voltage relative to GND(1)	Commercial	1.8 – 5%	1.8 + 5%	V
		Industrial	1.8 – 5%	1.8 + 5%	V
V_{CCO}	Supply voltage relative to GND(2)	Commercial	1.2	3.6	V
		Industrial	1.2	3.6	V
T_{IN}	Input signal transition time(3)		-	250	ns

Notes:
1. Functional operation is guaranteed down to a minimum V_{CCINT} of 1.62V (Nominal V_{CCINT} –10%). For every 50 mV reduction in V_{CCINT} below 1.71V (nominal V_{CCINT} –5%), all delay parameters increase by approximately 3%.
2. Minimum and maximum values for V_{CCO} vary according to the I/O standard selected.
3. Input and output measurement threshold is ~50% of V_{CCO}.

DC Characteristics Over Operating Conditions

Symbol	Description			Min	Typ	Max	Units
V_{DRINT}	Data retention V_{CCINT} voltage (below which configuration data may be lost)			1.5	-	-	V
V_{DRIO}	Data retention V_{CCO} voltage (below which configuration data may be lost)			1.2	-	-	V
I_{CCINTQ}	Quiescent V_{CCINT} supply current(1)	XC2S50E	Commercial	-	10	200	mA
			Industrial	-	10	200	mA
		XC2S100E	Commercial	-	10	200	mA
			Industrial	-	10	200	mA
		XC2S150E	Commercial	-	10	300	mA
			Industrial	-	10	300	mA
		XC2S200E	Commercial	-	10	300	mA
			Industrial	-	10	300	mA
		XC2S300E	Commercial	-	12	300	mA
			Industrial	-	12	300	mA
		XC2S400E	Commercial	-	15	300	mA
			Industrial	-	15	300	mA
		XC2S600E	Commercial	-	15	400	mA
			Industrial	-	15	400	mA
I_{CCOQ}	Quiescent V_{CCO} supply current(1)			-	-	2	mA
I_{REF}	V_{REF} current per V_{REF} pin			-	-	20	µA
I_L	Input or output leakage current per pin			–10	-	+10	µA
C_{IN}	Input capacitance (sample tested)	TQ, PQ, FG, FT packages		-	-	8	pF
I_{RPU}	Pad pull-up (when selected) @ V_{IN} = 0V, V_{CCO} = 3.3V (sample tested)(2)			-	-	0.25	mA
I_{RPD}	Pad pull-down (when selected) @ V_{IN} = 3.6V (sample tested)(2)			-	-	0.25	mA

Notes:
1. With no output current loads, no active input pull-up resistors, all I/O pins 3-stated and floating.
2. Internal pull-up and pull-down resistors guarantee valid logic levels at unconnected input pins. These pull-up and pull-down resistors do not provide valid logic levels when input pins are connected to other circuits.

Power-On Requirements

Spartan™-IIE FPGAs require that a minimum supply current I_{CCPO} be provided to the V_{CCINT} lines for a successful power-on. If more current is available, the FPGA can consume more than I_{CCPO} min., though this cannot adversely affect reliability.

A maximum limit for I_{CCPO} is not specified. Be careful when using foldback/crowbar supplies and fuses. It is possible to control the magnitude of I_{CCPO} by limiting the supply current available to the FPGA. A current limit below the trip level will avoid inadvertently activating over-current protection circuits.

Symbol	Description				Min(1)	Typ	Max	Units
I_{CCPO}	Total V_{CCINT} supply current required during power-on	Commercial	XC2S50E - XC2S300E	After PCN(2)	300	-	-	mA
				Before PCN(2)	500	-	-	mA
			XC2S400E - XC2S600E		500	-	-	mA
		Industrial	XC2S50E - XC2S300E	After PCN(2)	500	-	-	mA
				Before PCN(2)	2	-	-	A
			XC2S400E - XC2S600E		700	-	-	mA
T_{CCPO}	V_{CCINT}(3,4) ramp time		After PCN(2)		500	-	-	µs
			Before PCN(2)		2	-	50	ms
I_{HSPO}	AC current per pin during power-on in hot-swap applications when $V_{IN} > V_{CCO} + 0.4V$; duration < 10ns		After PCN(2)		-	±60	-	µA

Notes:
1. The I_{CCPO} requirement applies for a brief time (commonly only a few milliseconds) when V_{CCINT} ramps from 0 to 1.8V.
2. Devices built after the Product Change Notice PCN 2002-05 (see **http://www.xilinx.com/bvdocs/notifications/pcn2002-05.pdf**) have improved power-on requirements. Devices after the PCN have a 'T' preceding the date code as referenced in the PCN. Note that the XC2S150E, XC2S400E, and XC2S600E always have this mark. Devices before the PCN have an 'S' preceding the date code. Note that devices before the PCN are measured with V_{CCINT} and V_{CCO} powering up simultaneously.
3. The ramp time is measured from GND to 1.8V on a fully loaded board.
4. V_{CCINT} must not dip in the negative direction during power on.
5. I/Os are not guaranteed to be disabled until V_{CCINT} is applied.
6. For more information on designing to meet the power-on specifications, refer to the application note **XAPP450 "Power-On Current Requirements for the Spartan-II and Spartan-IIE Families"**.

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for V_{OL} and V_{OH} are guaranteed output voltages over the recommended operating conditions. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective I_{OL} and I_{OH} currents shown. Other standards are sample tested.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTL(1)	–0.5	0.8	2.0	3.6	0.4	2.4	24	–24
LVCMOS2	–0.5	0.7	1.7	2.7	0.4	1.9	12	–12
LVCMOS18	–0.5	35% V_{CCO}	65% V_{CCO}	1.95	0.4	V_{CCO} – 0.4	8	–8
PCI, 3.3V	–0.5	30% V_{CCO}	50% V_{CCO}	V_{CCO} + 0.5	10% V_{CCO}	90% V_{CCO}	Note (2)	Note (2)
GTL	–0.5	V_{REF} – 0.05	V_{REF} + 0.05	3.6	0.4	-	40	-
GTL+	–0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.6	-	36	-
HSTL I	–0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	8	–8

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
HSTL III	–0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	24	–8
HSTL IV	–0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	48	–8
SSTL3 I	–0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.6	V_{REF} + 0.6	8	–8
SSTL3 II	–0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.8	V_{REF} + 0.8	16	–16
SSTL2 I	–0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.61	V_{REF} + 0.61	7.6	–7.6
SSTL2 II	–0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.8	V_{REF} + 0.8	15.2	–15.2
CTT	–0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.4	V_{REF} + 0.4	8	–8
AGP	–0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	10% V_{CCO}	90% V_{CCO}	Note (2)	Note (2)

Notes:
1. V_{OL} and V_{OH} for lower drive currents are sample tested.
2. Tested according to the relevant specifications.

LVDS DC Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
V_{CCO}	Supply voltage		2.375	2.5	2.625	V
V_{OH}	Output High voltage for Q and $\overline{Q}$	R_T = 100Ω across Q and $\overline{Q}$ signals	1.25	1.425	1.6	V
V_{OL}	Output Low voltage for Q and $\overline{Q}$	R_T = 100Ω across Q and $\overline{Q}$ signals	0.9	1.075	1.25	V
V_{ODIFF}	Differential output voltage (Q – $\overline{Q}$), Q = High or ($\overline{Q}$ – Q), $\overline{Q}$ = High	R_T = 100Ω across Q and $\overline{Q}$ signals	250	350	450	mV
V_{OCM}	Output common-mode voltage	R_T = 100Ω across Q and $\overline{Q}$ signals	1.125	1.25	1.375	V
V_{IDIFF}	Differential input voltage (Q – $\overline{Q}$), Q = High or ($\overline{Q}$ – Q), $\overline{Q}$ = High	Common-mode input voltage = 1.25 V	100	350	-	mV
V_{ICM}	Input common-mode voltage	Differential input voltage = ±350 mV	0.2	1.25	2.2	V

LVPECL DC Specifications

These values are valid at the output of the source termination pack shown under LVPECL, with a 100Ω differential load only. The V_{OH} levels are 200 mV below standard LVPECL levels and are compatible with devices tolerant of lower common-mode ranges. The following table summarizes the DC output specifications of LVPECL.

DC Parameter	Min	Max	Min	Max	Min	Max	Units
V_{CCO}	3.0		3.3		3.6		V
V_{OH}	1.8	2.11	1.92	2.28	2.13	2.41	V
V_{OL}	0.96	1.27	1.06	1.43	1.30	1.57	V
V_{IH}	1.49	2.72	1.49	2.72	1.49	2.72	V
V_{IL}	0.86	2.125	0.86	2.125	0.86	2.125	V
Differential input voltage	0.3	-	0.3	-	0.3	-	V

Switching Characteristics

Internal timing parameters are derived from measuring internal test patterns. Listed below are representative values. For more specific, more precise, and worst-case guaranteed data, use the values reported by the static timing analyzer (TRACE in the Xilinx Development System) and back-annotated to the simulation netlist. All timing parameters assume worst-case operating conditions (supply voltage and junction temperature). Values apply to all Spartan-IIE devices unless otherwise noted.

Global Clock Input to Output Delay for LVTTL, *with* DLL (Pin-to-Pin)(1)

Symbol	Description	Speed Grade			Units
		All	-7	-6	
		Min	Max	Max	
$T_{ICKOFDLL}$	LVTTL global clock input to output delay using output flip-flop for LVTTL, 12 mA, fast slew rate, *with* DLL.	1.0	3.1	3.1	ns

Notes:
1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 50% V_{CC} threshold with 35 pF external capacitive load for LVTTL. The 35 pF load does not apply to the Min values. For other I/O standards and different loads, see the tables **Constants for Calculating T_{IOOP}** and **Delay Measurement Methodology**, page 11.
3. DLL output jitter is already included in the timing calculation.
4. For data *output* with different standards, adjust delays with the values shown in **IOB Output Delay Adjustments for Different Standards(1)**, page 10. For a global clock input with standards other than LVTTL, adjust delays with values from the **I/O Standard Global Clock Input Adjustments**, page 12.

Global Clock Input to Output Delay for LVTTL, *without* DLL (Pin-to-Pin)(1)

Symbol	Description	Device	Speed Grade			Units
			All	-7	-6	
			Min	Max	Max	
T_{ICKOF}	LVTTL global clock input to output delay using output flip-flop for LVTTL, 12 mA, fast slew rate, *without* DLL.	XC2S50E	1.5	4.4	4.6	ns
		XC2S100E	1.5	4.4	4.6	ns
		XC2S150E	1.5	4.5	4.7	ns
		XC2S200E	1.5	4.5	4.7	ns
		XC2S300E	1.5	4.5	4.7	ns
		XC2S400E	1.5	4.6	4.8	ns
		XC2S600E	1.6	4.7	4.9	ns

Notes:
1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 50% V_{CC} threshold with 35 pF external capacitive load for LVTTL. The 35 pF load does not apply to the Min values. For other I/O standards and different loads, see the tables **Constants for Calculating T_{IOOP}** and **Delay Measurement Methodology**, page 11.
3. For data *output* with different standards, adjust delays with the values shown in **IOB Output Delay Adjustments for Different Standards(1)**, page 10. For a global clock input with standards other than LVTTL, adjust delays with values from the **I/O Standard Global Clock Input Adjustments**, page 12.

Global Clock Setup and Hold for LVTTL Standard, *with* DLL (Pin-to-Pin)

Symbol	Description	Speed Grade		Units
		-7	-6	
		Min	Min	
T_{PSDLL} / T_{PHDLL}	Input setup and hold time relative to global clock input signal for LVTTL standard, no delay, IFF,(1) *with* DLL	1.6 / 0	1.7 / 0	ns

Notes:
1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. DLL output jitter is already included in the timing calculation.
4. For data input with different standards, adjust the setup time delay by the values shown in **IOB Input Delay Adjustments for Different Standards**, page 8. For a global clock input with standards other than LVTTL, adjust delays with values from the **I/O Standard Global Clock Input Adjustments**, page 12.
5. A zero hold time listing indicates no hold time or a negative hold time.

Global Clock Setup and Hold for LVTTL Standard, *without* DLL (Pin-to-Pin)

Symbol	Description	Device	Speed Grade		Units
			-7	-6	
			Min	Min	
T_{PSFD} / T_{PHFD}	Input setup and hold time relative to global clock input signal for LVTTL standard, with delay, IFF,(1) *without* DLL	XC2S50E	1.8 / 0	1.8 / 0	ns
		XC2S100E	1.8 / 0	1.8 / 0	ns
		XC2S150E	1.9 / 0	1.9 / 0	ns
		XC2S200E	1.9 / 0	1.9 / 0	ns
		XC2S300E	2.0 / 0	2.0 / 0	ns
		XC2S400E	2.0 / 0	2.0 / 0	ns
		XC2S600E	2.1 / 0	2.1 / 0	ns

Notes:
1. IFF = Input Flip-Flop or Latch
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. For data input with different standards, adjust the setup time delay by the values shown in **IOB Input Delay Adjustments for Different Standards**, page 8. For a global clock input with standards other than LVTTL, adjust delays with values from the **I/O Standard Global Clock Input Adjustments**, page 12.

IOB Input Switching Characteristics(1)

Input delays associated with the pad are specified for LVTTL levels. For other standards, adjust the delays with the values shown in **IOB Input Delay Adjustments for Different Standards**, page 8.

Symbol	Description	Device	Speed Grade				Units
			-7		-6		
			Min	Max	Min	Max	
Propagation Delays							
T_{IOPI}	Pad to I output, no delay	All	0.4	0.8	0.4	0.8	ns
T_{IOPID}	Pad to I output, with delay	All	0.5	1.0	0.5	1.0	ns
T_{IOPLI}	Pad to output IQ via transparent latch, no delay	All	0.7	1.5	0.7	1.6	ns
T_{IOPLID}	Pad to output IQ via transparent latch, with delay	XC2S50E	1.3	3.0	1.3	3.1	ns
		XC2S100E	1.3	3.0	1.3	3.1	ns
		XC2S150E	1.3	3.2	1.3	3.3	ns
		XC2S200E	1.3	3.2	1.3	3.3	ns
		XC2S300E	1.3	3.2	1.3	3.3	ns
		XC2S400E	1.4	3.2	1.4	3.4	ns
		XC2S600E	1.5	3.5	1.5	3.7	ns
Sequential Delays							
T_{IOCKIQ}	Clock CLK to output IQ	All	0.1	0.7	0.1	0.7	ns
Setup/Hold Times with Respect to Clock CLK							
T_{IOPICK} / T_{IOICKP}	Pad, no delay	All	1.4 / 0	-	1.5 / 0	-	ns
$T_{IOPICKD}$ / $T_{IOICKPD}$	Pad, with delay	XC2S50E	2.9 / 0	-	2.9 / 0	-	ns
		XC2S100E	2.9 / 0	-	2.9 / 0	-	ns
		XC2S150E	3.1 / 0	-	3.1 / 0	-	ns
		XC2S200E	3.1 / 0	-	3.1 / 0	-	ns
		XC2S300E	3.1 / 0	-	3.1 / 0	-	ns
		XC2S400E	3.2 / 0	-	3.2 / 0	-	ns
		XC2S600E	3.5 / 0	-	3.5 / 0	-	ns
$T_{IOICECK}$ / $T_{IOCKICE}$	ICE input	All	0.7 / 0.01	-	0.7 / 0.01	-	ns
Set/Reset Delays							
$T_{IOSRCKI}$	SR input (IFF, synchronous)	All	0.9	-	1.0	-	ns
T_{IOSRIQ}	SR input to IQ (asynchronous)	All	0.5	1.2	0.5	1.4	ns
T_{GSRQ}	GSR to output IQ	All	3.8	8.5	3.8	9.7	ns

Notes:
1. Input timing for LVTTL is measured at 1.4V. For other I/O standards, see the table **Delay Measurement Methodology**, page 11.

IOB Input Delay Adjustments for Different Standards

Input delays associated with the pad are specified for LVTTL. For other standards, adjust the delays by the values shown. A delay adjusted in this way constitutes a worst-case limit.

Symbol	Description	Standard	Speed Grade		Units
			-7	-6	
Data Input Delay Adjustments					
T_{ILVTTL}	Standard-specific data input delay adjustments	LVTTL	0	0	ns
$T_{ILVCMOS2}$		LVCMOS2	0	0	ns
$T_{ILVCMOS18}$		LVCMOS18	0.20	0.20	ns
T_{ILVDS}		LVDS	0.15	0.15	ns
$T_{ILVPECL}$		LVPECL	0.15	0.15	ns
T_{IPCI33_3}		PCI, 33 MHz, 3.3V	0.08	0.08	ns
T_{IPCI66_3}		PCI, 66 MHz, 3.3V	–0.11	–0.11	ns
T_{IGTL}		GTL	0.14	0.14	ns
T_{IGTLP}		GTL+	0.14	0.14	ns
T_{IHSTL}		HSTL	0.04	0.04	ns
T_{ISSTL2}		SSTL2	0.04	0.04	ns
T_{ISSTL3}		SSTL3	0.04	0.04	ns
T_{ICTT}		CTT	0.10	0.10	ns
T_{IAGP}		AGP	0.04	0.04	ns

IOB Output Switching Characteristics

Output delays terminating at a pad are specified for LVTTL with 12 mA drive and fast slew rate. For other standards, adjust the delays with the values shown in **IOB Output Delay Adjustments for Different Standards(1)**, page 10.

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Propagation Delays						
T_{IOOP}	O input to pad	1.0	2.7	1.0	2.9	ns
T_{IOOLP}	O input to pad via transparent latch	1.2	3.1	1.2	3.4	ns
3-state Delays						
T_{IOTHZ}	T input to pad high impedance(1)	0.7	1.7	0.7	1.9	ns
T_{IOTON}	T input to valid data on pad	1.1	2.9	1.1	3.1	ns
$T_{IOTLPHZ}$	T input to pad high impedance via transparent latch(1)	0.8	2.0	0.8	2.2	ns
$T_{IOTLPON}$	T input to valid data on pad via transparent latch	1.2	3.2	1.2	3.4	ns
T_{GTS}	GTS to pad high impedance(1)	1.9	4.6	1.9	4.9	ns
Sequential Delays						
T_{IOCKP}	Clock CLK to pad	0.9	2.8	0.9	2.9	ns
T_{IOCKHZ}	Clock CLK to pad high impedance (synchronous)(1)	0.7	2.0	0.7	2.2	ns
T_{IOCKON}	Clock CLK to valid data on pad (synchronous)	1.1	3.2	1.1	3.4	ns
Setup/Hold Times with Respect to Clock CLK						
T_{IOOCK} / T_{IOCKO}	O input	1.0 / 0	-	1.1 / 0	-	ns
$T_{IOOCECK}$ / $T_{IOCKOCE}$	OCE input	0.7 / 0	-	0.7 / 0	-	ns
$T_{IOSRCKO}$ / $T_{IOCKOSR}$	SR input (OFF)	0.9 / 0	-	1.0 / 0	-	ns
T_{IOTCK} / T_{IOCKT}	3-state setup times, T input	0.6 / 0	-	0.7 / 0	-	ns
$T_{IOTCECK}$ / $T_{IOCKTCE}$	3-state setup times, TCE input	0.6 / 0	-	0.8 / 0	-	ns
$T_{IOSRCKT}$ / $T_{IOCKTSR}$	3-state setup times, SR input (TFF)	0.9 / 0	-	1.0 / 0	-	ns
Set/Reset Delays						
T_{IOSRP}	SR input to pad (asynchronous)	1.2	3.3	1.2	3.5	ns
T_{IOSRHZ}	SR input to pad high impedance (asynchronous)(1)	1.0	2.4	1.0	2.7	ns
T_{IOSRON}	SR input to valid data on pad (asynchronous)	1.4	3.7	1.4	3.9	ns
T_{IOGSRQ}	GSR to pad	3.8	8.5	3.8	9.7	ns

Notes:
1. Three-state turn-off delays should not be adjusted.

IOB Output Delay Adjustments for Different Standards(1)

Output delays terminating at a pad are specified for LVTTL with 12 mA drive and fast slew rate. For other standards, adjust the delays by the values shown. A delay adjusted in this way constitutes a worst-case limit.

Symbol	Description	Standard	Speed Grade		Units
			-7	-6	
Output Delay Adjustments (Adj)					
T_{OLVTTL_S2}	Standard-specific adjustments for output delays terminating at pads (based on standard capacitive load, C_{SL})	LVTTL, Slow, 2 mA	14.7	14.7	ns
T_{OLVTTL_S4}		4 mA	7.5	7.5	ns
T_{OLVTTL_S6}		6 mA	4.8	4.8	ns
T_{OLVTTL_S8}		8 mA	3.0	3.0	ns
T_{OLVTTL_S12}		12 mA	1.9	1.9	ns
T_{OLVTTL_S16}		16 mA	1.7	1.7	ns
T_{OLVTTL_S24}		24 mA	1.3	1.3	ns
T_{OLVTTL_F2}		LVTTL, Fast, 2 mA	13.1	13.1	ns
T_{OLVTTL_F4}		4 mA	5.3	5.3	ns
T_{OLVTTL_F6}		6 mA	3.1	3.1	ns
T_{OLVTTL_F8}		8 mA	1.0	1.0	ns
T_{OLVTTL_F12}		12 mA	0	0	ns
T_{OLVTTL_F16}		16 mA	–0.05	–0.05	ns
T_{OLVTTL_F24}		24 mA	–0.20	–0.20	ns
$T_{OLVCMOS2}$		LVCMOS2	0.09	0.09	ns
$T_{OLVCMOS18}$		LVCMOS18	0.7	0.7	ns
T_{OLVDS}		LVDS	–1.2	–1.2	ns
$T_{OLVPECL}$		LVPECL	–0.41	–0.41	ns
T_{OPCI33_3}		PCI, 33 MHz, 3.3V	2.3	2.3	ns
T_{OPCI66_3}		PCI, 66 MHz, 3.3V	–0.41	–0.41	ns
T_{OGTL}		GTL	0.49	0.49	ns
T_{OGTLP}		GTL+	0.8	0.8	ns
T_{OHSTL_I}		HSTL I	–0.51	–0.51	ns
T_{OHSTL_III}		HSTL III	–0.91	–0.91	ns
T_{OHSTL_IV}		HSTL IV	–1.01	–1.01	ns
T_{OSSTL2_I}		SSTL2 I	–0.51	–0.51	ns
T_{OSSLT2_II}		SSTL2 II	–0.91	–0.91	ns
T_{OSSTL3_I}		SSTL3 I	–0.51	–0.51	ns
T_{OSSTL3_II}		SSTL3 II	–1.01	–1.01	ns
T_{OCTT}		CTT	–0.61	–0.61	ns
T_{OAGP}		AGP	–0.91	–0.91	ns

Notes:

1. Output timing is measured at 1.4V with 35 pF external capacitive load for LVTTL. For other I/O standards and different loads, see the tables **Constants for Calculating T_{IOOP}** and **Delay Measurement Methodology**, page 11.

Calculation of T_{IOOP} as a Function of Capacitance

T_{IOOP} is the propagation delay from the O Input of the IOB to the pad. The values for T_{IOOP} are based on the standard capacitive load (C_{SL}) for each I/O standard as listed in the table **Constants for Calculating T_{IOOP}**, below.

For other capacitive loads, use the formulas below to calculate an adjusted propagation delay, T_{IOOP1}.

$$T_{IOOP1} = T_{IOOP} + Adj + (C_{LOAD} - C_{SL}) * F_L$$

Where:

- Adj is selected from **IOB Output Delay Adjustments for Different Standards(1)**, page 10, according to the I/O standard used
- C_{LOAD} is the capacitive load for the design
- F_L is the capacitance scaling factor

Delay Measurement Methodology

Standard	V_L (1)	V_H (1)	Meas. Point	V_{REF} Typ (2)
LVTTL	0	3	1.4	-
LVCMOS2	0	2.5	1.125	-
PCI33_3	Per PCI Spec			-
PCI66_3	Per PCI Spec			-
GTL	V_{REF} – 0.2	V_{REF} + 0.2	V_{REF}	0.80
GTL+	V_{REF} – 0.2	V_{REF} + 0.2	V_{REF}	1.0
HSTL Class I	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	0.75
HSTL Class III	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	0.90
HSTL Class IV	V_{REF} – 0.5	V_{REF} + 0.5	V_{REF}	0.90
SSTL3 I and II	V_{REF} – 1.0	V_{REF} + 1.0	V_{REF}	1.5
SSTL2 I and II	V_{REF} – 0.75	V_{REF} + 0.75	V_{REF}	1.25
CTT	V_{REF} – 0.2	V_{REF} + 0.2	V_{REF}	1.5
AGP	V_{REF} – (0.2xV_{CCO})	V_{REF} + (0.2xV_{CCO})	V_{REF}	Per AGP Spec
LVDS	1.2 – 0.125	1.2 + 0.125	1.2	
LVPECL	1.6 – 0.3	1.6 + 0.3	1.6	

Notes:

1. Input waveform switches between V_L and V_H.
2. Measurements are made at V_{REF} Typ, Maximum, and Minimum. Worst-case values are reported.
3. I/O parameter measurements are made with the capacitance values shown in the following table, **Constants for Calculating T_{IOOP}**. Refer to Application Note **XAPP179** for appropriate terminations.
4. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

Constants for Calculating T_{IOOP}

Standard	C_{SL} (1) (pF)	F_L (ns/pF)
LVTTL Fast Slew Rate, 2 mA drive	35	0.41
LVTTL Fast Slew Rate, 4 mA drive	35	0.20
LVTTL Fast Slew Rate, 6 mA drive	35	0.13
LVTTL Fast Slew Rate, 8 mA drive	35	0.079
LVTTL Fast Slew Rate, 12 mA drive	35	0.044
LVTTL Fast Slew Rate, 16 mA drive	35	0.043
LVTTL Fast Slew Rate, 24 mA drive	35	0.033
LVTTL Slow Slew Rate, 2 mA drive	35	0.41
LVTTL Slow Slew Rate, 4 mA drive	35	0.20
LVTTL Slow Slew Rate, 6 mA drive	35	0.100
LVTTL Slow Slew Rate, 8 mA drive	35	0.086
LVTTL Slow Slew Rate, 12 mA drive	35	0.058
LVTTL Slow Slew Rate, 16 mA drive	35	0.050
LVTTL Slow Slew Rate, 24 mA drive	35	0.048
LVCMOS2	35	0.041
LVCMOS18	35	0.050
PCI 33 MHz 3.3V	10	0.050
PCI 66 MHz 3.3V	10	0.033
GTL	0	0.014
GTL+	0	0.017
HSTL Class I	20	0.022
HSTL Class III	20	0.016
HSTL Class IV	20	0.014
SSTL2 Class I	30	0.028
SSTL2 Class II	30	0.016
SSTL3 Class I	30	0.029
SSTL3 Class II	30	0.016
CTT	20	0.035
AGP	10	0.037

Notes:

1. I/O parameter measurements are made with the capacitance values shown above. Refer to Application Note **XAPP179** for appropriate terminations.
2. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

Clock Distribution Switching Characteristics

T_{GPIO} is specified for LVTTL levels. For other standards, adjust T_{GPIO} with the values shown in **I/O Standard Global Clock Input Adjustments**.

Symbol	Description	Speed Grade		Units
		-7	-6	
		Max	Max	
GCLK IOB and Buffer				
T_{GPIO}	Global clock pad to output	0.7	0.7	ns
T_{GIO}	Global clock buffer I input to O output	0.45	0.5	ns

I/O Standard Global Clock Input Adjustments

Delays associated with a global clock input pad are specified for LVTTL levels. For other standards, adjust the delays by the values shown. A delay adjusted in this way constitutes a worst-case limit.

Symbol	Description	Standard	Speed Grade		Units
			-7	-6	
Data Input Delay Adjustments					
$T_{GPLVTTL}$	Standard-specific global clock input delay adjustments	LVTTL	0	0	ns
$T_{GPLVCMOS2}$		LVCMOS2	0	0	ns
$T_{GPLVCMOS18}$		LVCMOS18	0.2	0.2	ns
$T_{GPLVCDS}$		LVDS	0.38	0.38	ns
$T_{GPLVPECL}$		LVCPECL	0.38	0.38	ns
$T_{GPPCI33\_3}$		PCI, 33 MHz, 3.3V	0.08	0.08	ns
$T_{GPPCI66\_3}$		PCI, 66 MHz, 3.3V	–0.11	–0.11	ns
T_{GPGTL}		GTL	0.37	0.37	ns
T_{GPGTLP}		GTL+	0.37	0.37	ns
T_{GPHSTL}		HSTL	0.27	0.27	ns
$T_{GPSSTL2}$		SSTL2	0.27	0.27	ns
$T_{GPSSTL3}$		SSTL3	0.27	0.27	ns
T_{GPCTT}		CTT	0.33	0.33	ns
T_{GPAGP}		AGP	0.27	0.27	ns

Notes:
1. Input timing for GPLVTTL is measured at 1.4V. For other I/O standards, see the table **Delay Measurement Methodology**, page 11.

DLL Timing Parameters

Because of the difficulty in directly measuring many internal timing parameters, those parameters are derived from benchmark timing patterns. The following guidelines reflect worst-case values across the recommended operating conditions.

Symbol	Description	F_{CLKIN}	Speed Grade				Units
			-7		-6		
			Min	Max	Min	Max	
$F_{CLKINHF}$	Input clock frequency (CLKDLLHF)	-	60	320	60	275	MHz
$F_{CLKINLF}$	Input clock frequency (CLKDLL)	-	25	160	25	135	MHz
T_{DLLPW}	Input clock pulse width	≥25 MHz	5.0	-	5.0	-	ns
		≥50 MHz	3.0	-	3.0	-	ns
		≥100 MHz	2.4	-	2.4	-	ns
		≥150 MHz	2.0	-	2.0	-	ns
		≥200 MHz	1.8	-	1.8	-	ns
		≥250 MHz	1.5	-	1.5	-	ns
		≥300 MHz	1.3	-	NA	-	

DLL Clock Tolerance, Jitter, and Phase Information

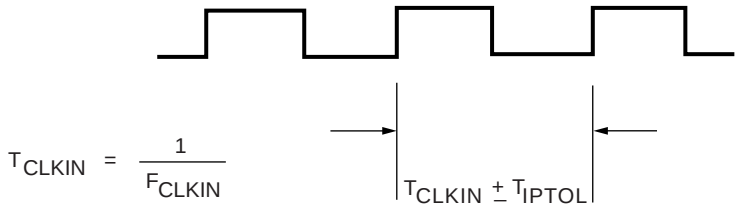
All DLL output jitter and phase specifications were determined through statistical measurement at the package pins using a clock mirror configuration and matched drivers. Figure 1, page 14, provides definitions for various parameters in the table below.

Symbol	Description	F_{CLKIN}	CLKDLLHF		CLKDLL		Units
			Min	Max	Min	Max	
T_{IPTOL}	Input clock period tolerance		-	1.0	-	1.0	ns
T_{IJITCC}	Input clock jitter tolerance (cycle-to-cycle)		-	±150	-	±300	ps
T_{LOCK}	Time required for DLL to acquire lock(1)	> 60 MHz	-	20	-	20	µs
		50-60 MHz	-	-	-	25	µs
		40-50 MHz	-	-	-	50	µs
		30-40 MHz	-	-	-	90	µs
		25-30 MHz	-	-	-	120	µs
T_{OJITCC}	Output jitter (cycle-to-cycle) for any DLL clock output(2)		-	±60	-	±60	ps
T_{PHIO}	Phase offset between CLKIN and CLKO(3)		-	±100	-	±100	ps
T_{PHOO}	Phase offset between clock outputs on the DLL(4)		-	±140	-	±140	ps
T_{PHIOM}	Phase difference between CLKIN and CLKO(5)		-	±160	-	±160	ps
T_{PHOOM}	Phase difference between clock outputs on the DLL(6)		-	±200	-	±200	ps

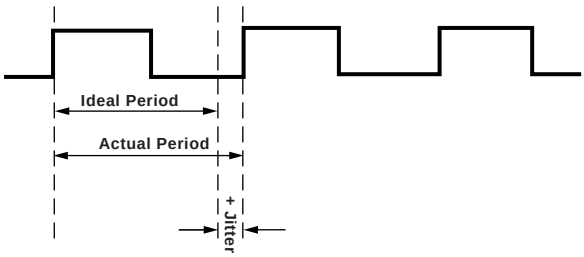
Notes:

1. Commercial operating conditions. Add 30% for Industrial operating conditions.
2. **Output Jitter** is cycle-to-cycle jitter measured on the DLL output clock, *excluding* input clock jitter.
3. **Phase Offset between CLKIN and CLKO** is the worst-case fixed time difference between rising edges of CLKIN and CLKO, *excluding* output jitter and input clock jitter.
4. **Phase Offset between Clock Outputs on the DLL** is the worst-case fixed time difference between rising edges of any two DLL outputs, *excluding* output jitter and input clock jitter.
5. **Maximum Phase Difference between CLKIN and CLKO** is the sum of output jitter and phase offset between CLKIN and CLKO, or the greatest difference between CLKIN and CLKO rising edges due to DLL alone (*excluding* input clock jitter).
6. **Maximum Phase Difference between Clock Outputs on the DLL** is the sum of output jitter and phase offset between any DLL clock outputs, or the greatest difference between any two DLL output rising edges due to DLL alone (*excluding* input clock jitter).

Period Tolerance: the allowed input clock period change in nanoseconds.



Output Jitter: the difference between an ideal reference clock edge and the actual design.



Phase Offset and Maximum Phase Difference

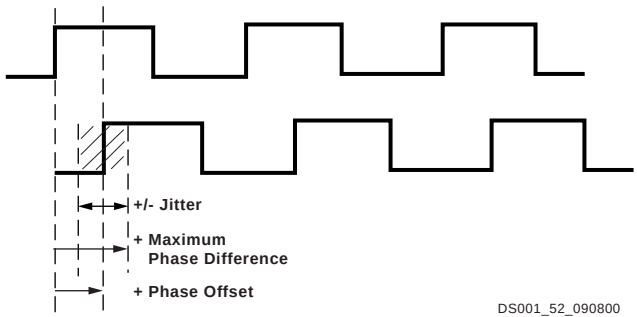


Figure 1: **Period Tolerance and Clock Jitter**

CLB Switching Characteristics

Delays originating at F/G inputs vary slightly according to the input used. The values listed below are worst-case. Precise values are provided by the timing analyzer.

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Combinatorial Delays						
T_{ILO}	4-input function: F/G inputs to X/Y outputs	0.18	0.42	0.18	0.47	ns
T_{IF5}	5-input function: F/G inputs to F5 output	0.3	0.8	0.3	0.9	ns
T_{IF5X}	5-input function: F/G inputs to X output	0.3	0.8	0.3	0.9	ns
T_{IF6Y}	6-input function: F/G inputs to Y output via F6 MUX	0.3	0.9	0.3	1.0	ns
T_{F5INY}	6-input function: F5IN input to Y output	0.04	0.2	0.04	0.22	ns
T_{IFNCTL}	Incremental delay routing through transparent latch to XQ/YQ outputs	-	0.7	-	0.8	ns
T_{BYYB}	BY input to YB output	0.18	0.46	0.18	0.51	ns
Sequential Delays						
T_{CKO}	FF clock CLK to XQ/YQ outputs	0.3	0.9	0.3	1.0	ns
T_{CKLO}	Latch clock CLK to XQ/YQ outputs	0.3	0.9	0.3	1.0	ns
Setup/Hold Times with Respect to Clock CLK						
T_{ICK} / T_{CKI}	4-input function: F/G inputs	1.0 / 0	-	1.1 / 0	-	ns
T_{IF5CK} / T_{CKIF5}	5-input function: F/G inputs	1.4 / 0	-	1.5 / 0	-	ns
T_{F5INCK} / T_{CKF5IN}	6-input function: F5IN input	0.8 / 0	-	0.8 / 0	-	ns
T_{IF6CK} / T_{CKIF6}	6-input function: F/G inputs via F6 MUX	1.5 / 0	-	1.6 / 0	-	ns
T_{DICK} / T_{CKDI}	BX/BY inputs	0.7 / 0	-	0.8 / 0	-	ns
T_{CECK} / T_{CKCE}	CE input	0.7 / 0	-	0.7 / 0	-	ns
T_{RCK} / T_{CKR}	SR/BY inputs (synchronous)	0.52 / 0	-	0.6 / 0	-	ns
Clock CLK						
T_{CH}	Pulse width, High	1.3	-	1.4	-	ns
T_{CL}	Pulse width, Low	1.3	-	1.4	-	ns
Set/Reset						
T_{RPW}	Pulse width, SR/BY inputs	2.1	-	2.4	-	ns
T_{RQ}	Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	0.3	0.9	0.3	1.0	ns
F_{TOG}	Toggle frequency (for export control)	-	400	-	357	MHz

CLB Arithmetic Switching Characteristics

Setup times not listed explicitly can be approximated by decreasing the combinatorial delays by the setup time adjustment listed. Precise values are provided by the timing analyzer.

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Combinatorial Delays						
T_{OPX}	F operand inputs to X via XOR	-	0.8	-	0.8	ns
T_{OPXB}	F operand input to XB output	-	0.8	-	0.9	ns
T_{OPY}	F operand input to Y via XOR	-	1.4	-	1.5	ns
T_{OPYB}	F operand input to YB output	-	1.1	-	1.3	ns
T_{OPCYF}	F operand input to COUT output	-	0.9	-	1.0	ns
T_{OPGY}	G operand inputs to Y via XOR	-	0.8	-	0.9	ns
T_{OPGYB}	G operand input to YB output	-	1.2	-	1.3	ns
T_{OPCYG}	G operand input to COUT output	-	0.9	-	1.0	ns
T_{BXCY}	BX initialization input to COUT	-	0.51	-	0.6	ns
T_{CINX}	CIN input to X output via XOR	-	0.6	-	0.7	ns
T_{CINXB}	CIN input to XB	-	0.07	-	0.1	ns
T_{CINY}	CIN input to Y via XOR	-	0.7	-	0.7	ns
T_{CINYB}	CIN input to YB	-	0.4	-	0.5	ns
T_{BYP}	CIN input to COUT output	-	0.14	-	0.15	ns
Multiplier Operation						
T_{FANDXB}	F1/2 operand inputs to XB output via AND	-	0.35	-	0.4	ns
T_{FANDYB}	F1/2 operand inputs to YB output via AND	-	0.7	-	0.8	ns
T_{FANDCY}	F1/2 operand inputs to COUT output via AND	-	0.5	-	0.6	ns
T_{GANDYB}	G1/2 operand inputs to YB output via AND	-	0.6	-	0.7	ns
T_{GANDCY}	G1/2 operand inputs to COUT output via AND	-	0.3	-	0.4	ns
Setup/Hold Times with Respect to Clock CLK						
T_{CCKX} / T_{CKCX}	CIN input to FFX	1.2 / 0	-	1.3 / 0	-	ns
T_{CCKY} / T_{CKCY}	CIN input to FFY	1.2 / 0	-	1.3 / 0	-	ns

CLB Distributed RAM Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
$T_{SHCKO16}$	Clock CLK to X/Y outputs (WE active, 16 x 1 mode)	0.6	1.5	0.6	1.7	ns
$T_{SHCKO32}$	Clock CLK to X/Y outputs (WE active, 32 x 1 mode)	0.8	1.9	0.8	2.1	ns
Setup/Hold Times with Respect to Clock CLK						
T_{AS} / T_{AH}	F/G address inputs	0.42 / 0	-	0.5 / 0	-	ns
T_{DS} / T_{DH}	BX/BY data inputs (DIN)	0.53 / 0	-	0.6 / 0	-	ns
T_{WS} / T_{WH}	CE input (WS)	0.7 / 0	-	0.8 / 0	-	ns
Clock CLK						
T_{WPH}	Pulse width, High	2.1	-	2.4	-	ns
T_{WPL}	Pulse width, Low	2.1	-	2.4	-	ns
T_{WC}	Clock period to meet address write cycle time	4.2	-	4.8	-	ns

CLB Shift Register Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
T_{REG}	Clock CLK to X/Y outputs	1.2	2.9	1.2	3.2	ns
Setup/Hold Times with Respect to Clock CLK						
T_{SHDICK}	BX/BY data inputs (DIN)	0.53 / 0	-	0.6 / 0	-	ns
T_{SHCECK}	CE input (WS)	0.7 / 0	-	0.8 / 0	-	ns
Clock CLK						
T_{SRPH}	Pulse width, High	2.1	-	2.4	-	ns
T_{SRPL}	Pulse width, Low	2.1	-	2.4	-	ns

Block RAM Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Sequential Delays						
T_{BCKO}	Clock CLK to DOUT output	0.6	3.1	0.6	3.5	ns
Setup/Hold Times with Respect to Clock CLK						
T_{BACK} / T_{BCKA}	ADDR inputs	1.0 / 0	-	1.1 / 0	-	ns
T_{BDCK}/ T_{BCKD}	DIN inputs	1.0 / 0	-	1.1 / 0	-	ns
T_{BECK}/ T_{BCKE}	EN inputs	2.2 / 0	-	2.5 / 0	-	ns
T_{BRCK}/ T_{BCKR}	RST input	2.1 / 0	-	2.3 / 0	-	ns
T_{BWCK}/ T_{BCKW}	WEN input	2.0 / 0	-	2.2 / 0	-	ns
Clock CLK						
T_{BPWH}	Pulse width, High	1.4	-	1.5	-	ns
T_{BPWL}	Pulse width, Low	1.4	-	1.5	-	ns
T_{BCCS}	CLKA -> CLKB setup time for different ports	2.7	-	3.0	-	ns

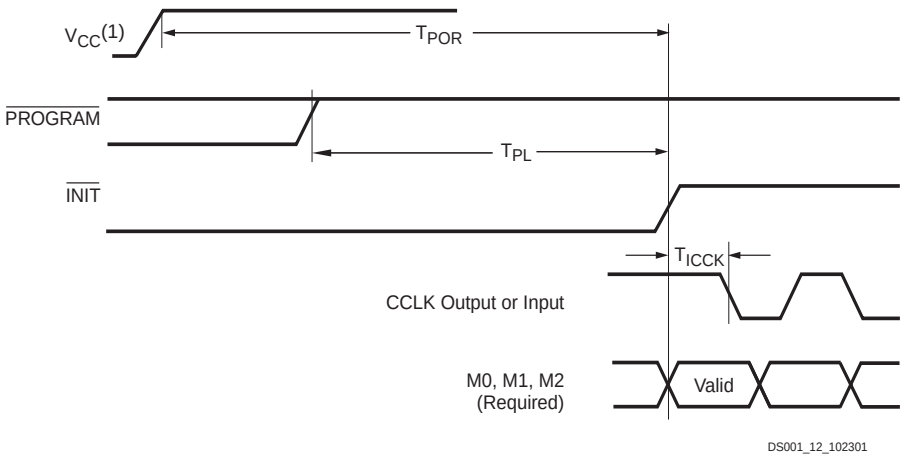
TBUF Switching Characteristics

Symbol	Description	Speed Grade		Units
		-7	-6	
		Max	Max	
T_{IO}	IN input to OUT output	0	0	ns
T_{OFF}	TRI input to OUT output high impedance	0.1	0.11	ns
T_{ON}	TRI input to valid data on OUT output	0.1	0.11	ns

JTAG Test Access Port Switching Characteristics

Symbol	Description	Speed Grade				Units
		-7		-6		
		Min	Max	Min	Max	
Setup/Hold Times with Respect to TCK						
T_{TAPTCK} / T_{TCKTAP}	TMS and TDI setup times and hold times	4.0 / 2.0	-	4.0 / 2.0	-	ns
Sequential Delays						
T_{TCKTDO}	Output delay from clock TCK to output TDO	-	11.0	-	11.0	ns
F_{TCK}	TCK clock frequency	-	33	-	33	MHz

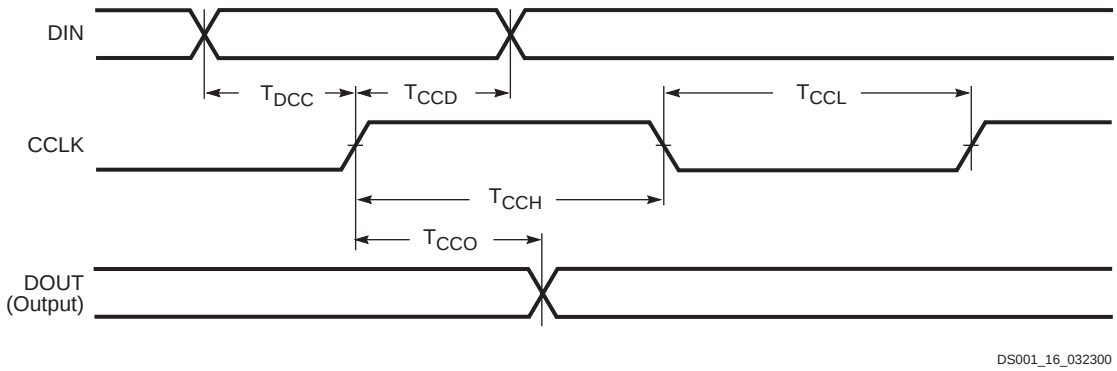
Configuration Switching Characteristics



Symbol	Description	All Devices		Units
		Min	Max	
T_{POR}	Power-on reset	-	2	ms
T_{PL}	Program latency	-	100	µs
T_{ICCK}	CCLK output delay (Master serial mode only)	0.5	4	µs
$T_{PROGRAM}$	Program pulse width	300	-	ns

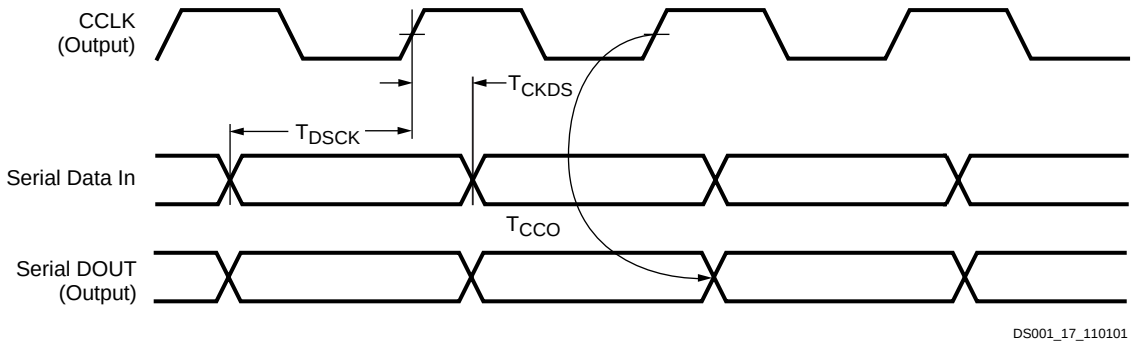
Notes:
1. Before configuration can begin, V_{CCINT} and V_{CCO} Bank 2 must reach the recommended operating voltage.

Figure 2: **Configuration Timing on Power-Up**



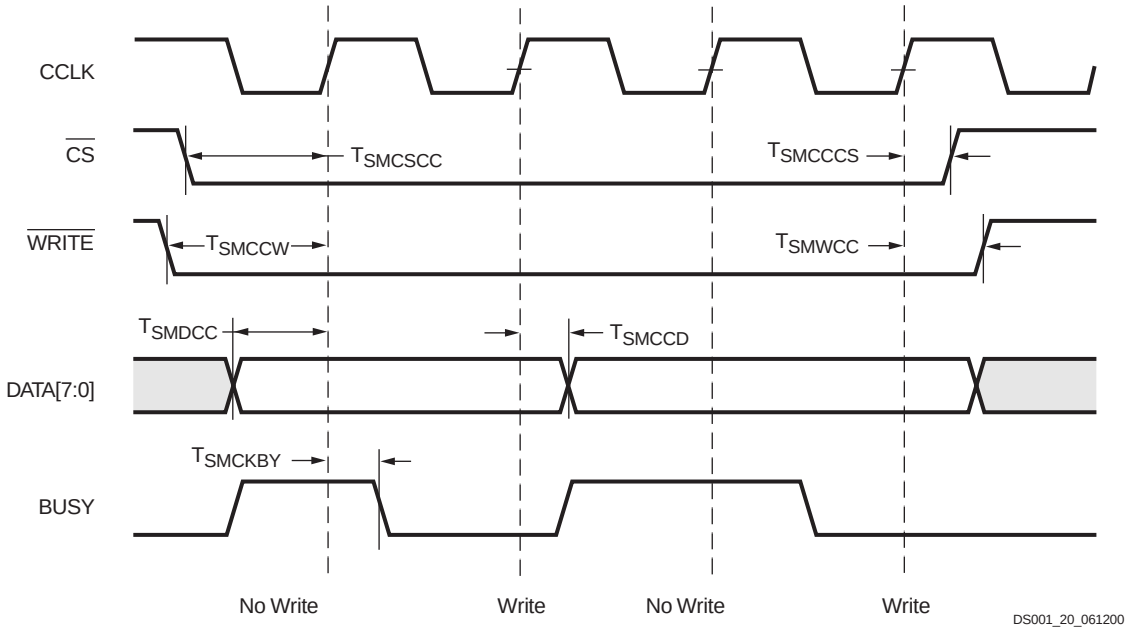
Symbol		Description	All Devices		Units
			Min	Max	
T_{DCC} / T_{CCD}	CCLK	DIN setup/hold	5 / 0	-	ns
T_{CCO}		DOUT	-	12	ns
T_{CCH}		High time	5	-	ns
T_{CCL}		Low time	5	-	ns
F_{CC}		Maximum frequency	-	66	MHz

Figure 3: **Slave Serial Mode Timing**



Symbol		Description	All Devices		Units
			Min	Max	
T_{DSCK} / T_{CKDS}	CCLK	DIN setup/hold	5 / 0	-	ns
T_{CCO}		DOUT	-	12	ns
F_{CC}		Frequency tolerance with respect to nominal	–30%	+45%	-

Figure 4: **Master Serial Mode Timing**



Symbol		Description	All Devices		Units
			Min	Max	
T_{SMDCC} / T_{SMCCD}	CCLK	D0-D7 setup/hold	5 / 1	-	ns
T_{SMCSCC} / T_{SMCCCS}		$\overline{CS}$ setup/hold	7 / 1	-	ns
T_{SMCCW} / T_{SMWCC}		$\overline{WRITE}$ setup/hold	7 / 1	-	ns
T_{SMCKBY}		BUSY propagation delay	-	12	ns
F_{CC}		Frequency	-	66	MHz
F_{CCNH}		Frequency with no handshake	-	50	MHz

Figure 5: **Slave Parallel (SelectMAP) Mode Write Timing**

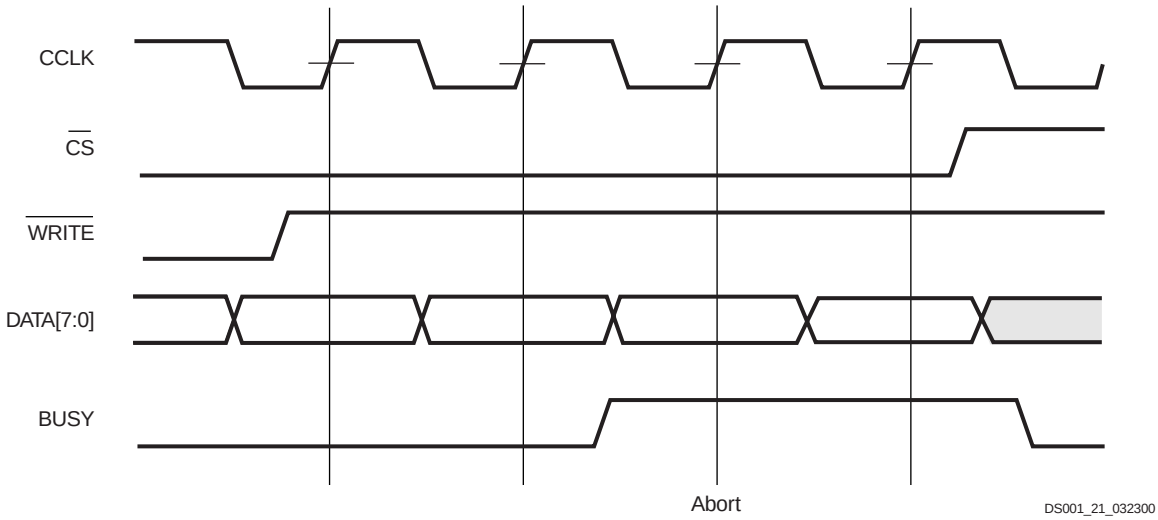


Figure 6: **Slave Parallel (SelectMAP) Mode Write Abort Waveforms**

Revision History

Version No.	Date	Description
1.0	11/15/01	Initial Xilinx release.
1.1	06/28/02	Added -7 speed grade and extended DLL specs to Industrial.
2.0	11/18/02	Added XC2S400E and XC2S600E. Added minimum specifications. Added reference to XAPP450 for Power-On Requirements. Removed Preliminary designation.
2.1	07/09/03	Added **ICCINTQ** typical values. Reduced **ICCPO** power-on current requirements. Relaxed **TCCPO** power-on ramp requirements. Added **IHSPO** to describe current in hot-swap applications. Updated **TPSFD / TPHFD** description to indicate use of delay element.

The Spartan-IIE Family Data Sheet

DS077-1, ***Spartan-IIE 1.8V FPGA Family: Introduction and Ordering Information*** (Module 1)

DS077-2, ***Spartan-IIE 1.8V FPGA Family: Functional Description*** (Module 2)

DS077-3, ***Spartan-IIE 1.8V FPGA Family: DC and Switching Characteristics*** (Module 3)

DS077-4, ***Spartan-IIE 1.8V FPGA Family: Pinout Tables*** (Module 4)